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November 2013

FCH47N60NF

N-Channel SupreMOS[®] FRFET[®] MOSFET 600 V, 45.8 A, 65 m Ω

Features

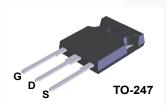
- 650 V @ T_{.1} = 150°C
- Typ. $R_{DS(on)}$ = 57.5 m Ω
- Ultra Low Gate Charge (Typ. Q_q = 240 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 420 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

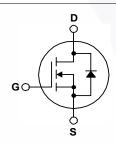
Application

- · Solar Inverter
- AC-DC Power Supply

Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SupreMOS FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol		Parameter		FCH47N60NF	Unit
V _{DSS}	Drain to Source Voltage			600	V
V _{GSS}	Gate to Source Voltage			±30	V
	Drain Current	- Continuous (T _C = 25°C)		45.8	_
ID	Drain Current	- Continuous (T _C = 100°C)	7	28.9	A
I _{DM}	Drain Current	- Pulsed (N	lote 1)	137.4	Α
E _{AS}	Single Pulsed Avalanche	Energy (N	lote 2)	2926	mJ
I _{AR}	Avalanche Current	(N	lote 1)	15.3	Α
E _{AR}	Repetitive Avalanche En	ergy (N	lote 1)	3.7	mJ
dv/dt	MOSFET dv/dt			100	V/ns
uv/ut	Peak Diode Recovery dv	r/dt (N	lote 3)	50	V/ns
П	Dower Dissination	(T _C = 25°C)		368	W
P_{D}	Power Dissipation	- Derate Above 25°C		2.94	W/°C
T _J , T _{STG}	Operating and Storage T	emperature Range		-55 to +150	°C
TL	Maximum Lead Tempera	ature for Soldering, 1/8" from Case for 5 Second	ds	300	°C

^{*}Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FCH47N60NF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.34	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	*C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH47N60NF	FCH47N60NF	TO-247	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}, T_C = 25^{\circ}\text{C}$	600	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.78	-	V/°C
1	Zero Gate Voltage Drain Current	V _{DS} = 480 V, V _{GS} = 0 V	-	-	10	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	100	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 23.5 A	-	57.5	65.0	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 23.5 A	-	52	100	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 400 V V 0 V	-	4600	6120	pF
C _{oss}	Output Capacitance	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz		195	260	pF
C _{rss}	Reverse Transfer Capacitance			3.0	5.0	pF
C _{oss}	Output Capacitance	V _{DS} = 380 V, V _{GS} = 0 V, f = 1 MHz	- \	108	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 380 V, V _{GS} = 0 V	-	492	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 23.5 A,	-	121	157	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	23	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	47	-	nC
ESR	Equivalent Series Resistance(G-S)	f = 1 MHz	-	0.9	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	34	78	ns
t _r		$V_{DD} = 380 \text{ V}, I_D = 23.5 \text{ A},$	-/	22	54	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 4.7 \Omega$	-	117	244	ns
t _f	Turn-Off Fall Time	(Note 4)	/ -	4	18	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	47	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	141	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 23.5 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 23.5 A,	-	169	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	1.3	-	μС

Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I_{AS} = 15.3 A, R_{G} = 25 Ω , starting T_{J} = 25°C.
- 3. $I_{SD} \le 45.8$ A, di/dt ≤ 1200 A/ μ s, $V_{DD} \le 380$ V, starting $T_J = 25^{\circ}C$.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

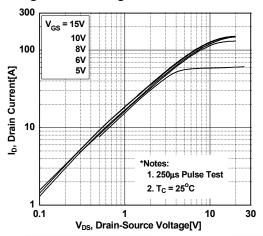


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

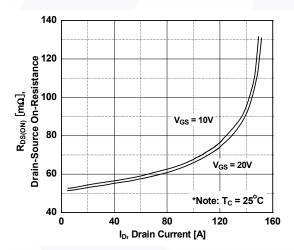


Figure 5. Capacitance Characteristics

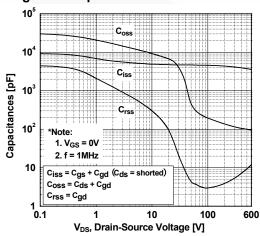


Figure 2. Transfer Characteristics

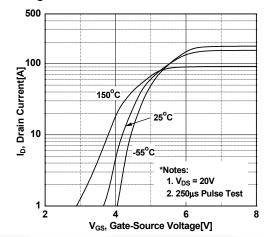


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

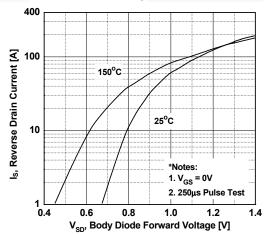
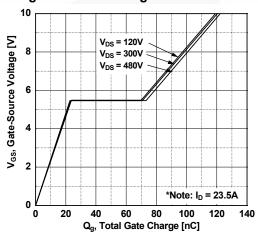


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

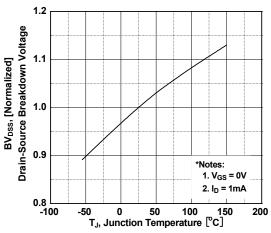


Figure 8. On-Resistance Variation vs. Temperature

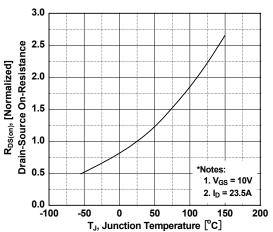


Figure 9. Maximum Safe Operating Area

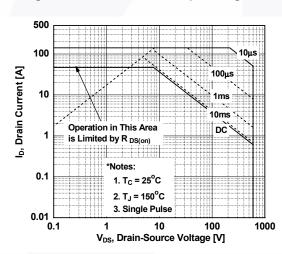


Figure 10. Maximum Drain Current vs. Case Temperature

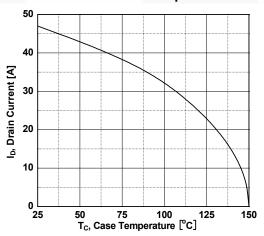
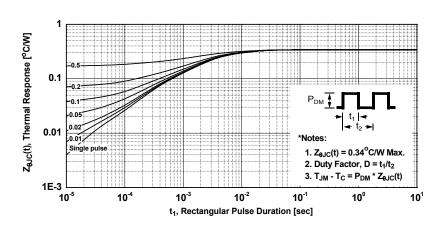


Figure 11. Transient Thermal Response Curve



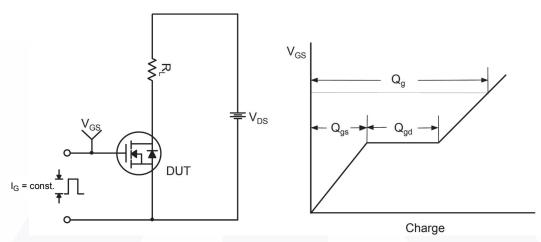


Figure 12. Gate Charge Test Circuit & Waveform

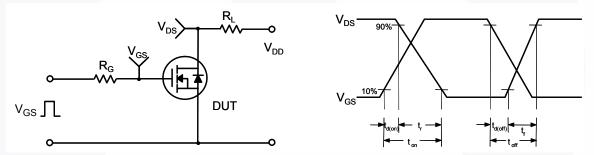


Figure 13. Resistive Switching Test Circuit & Waveforms

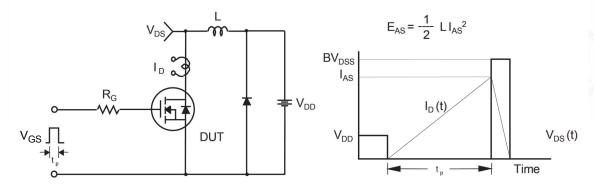


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

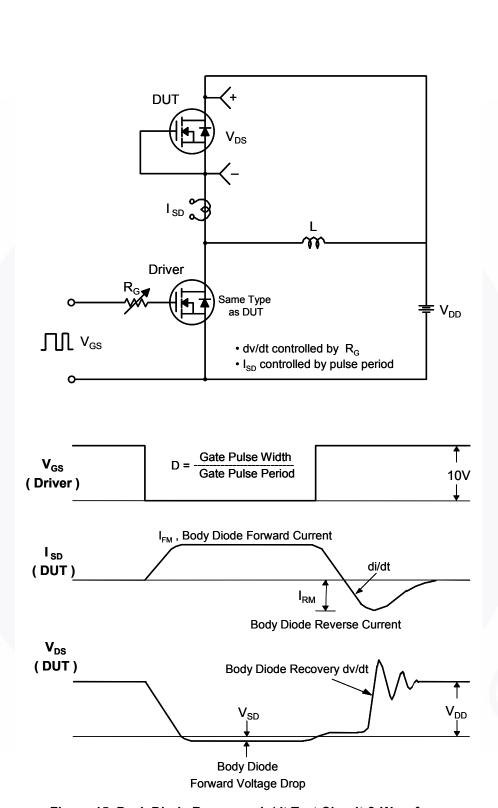
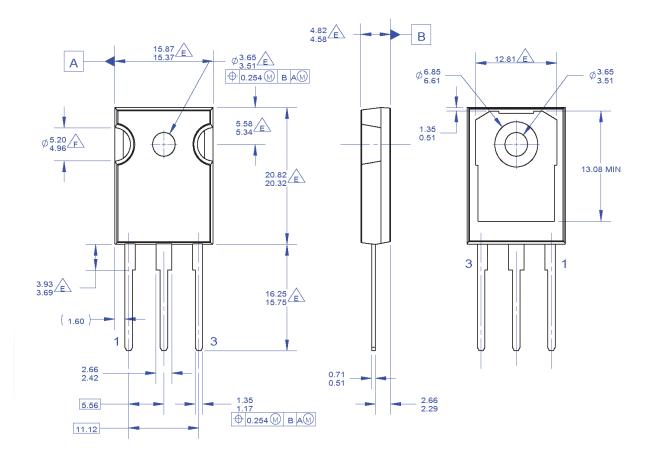


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

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G. DRAWING FILENAME: MKT-TO247A03_REV03

Figure 16. TO-247, Molded, 3-Lead, Jedec Variation AB

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